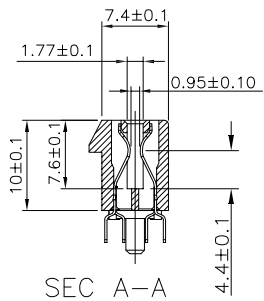


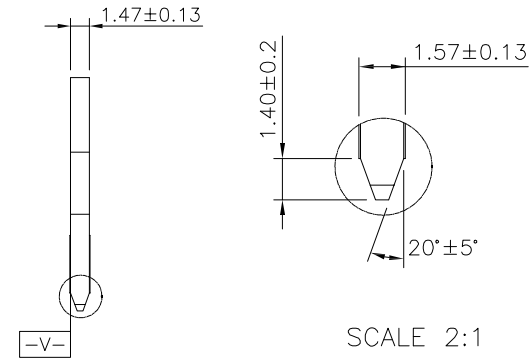
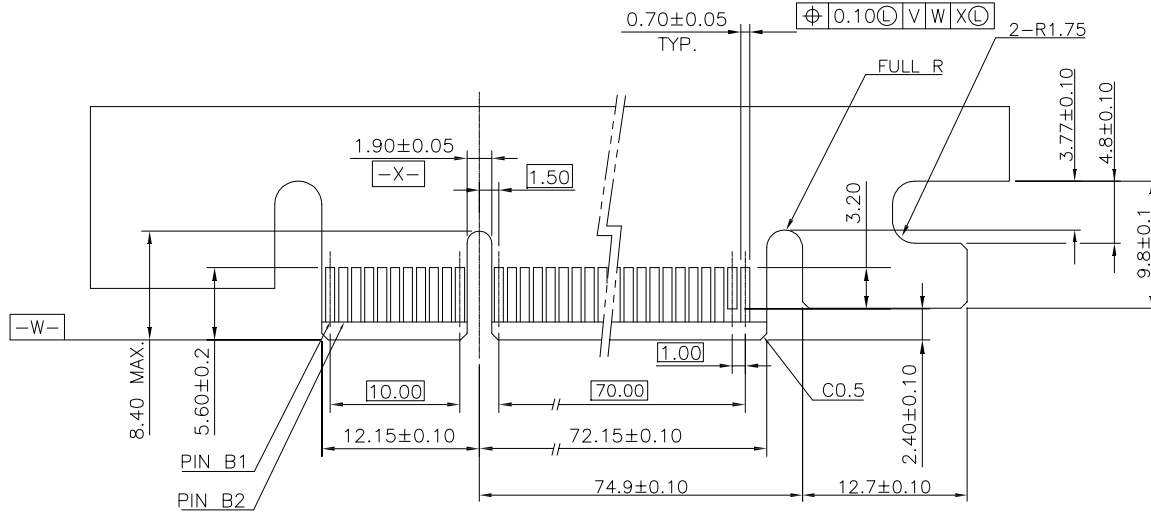
SEC B-B
SECALE 2:1



PART NUMBER	DIM.A
10083987-XXX13TLF	3.10±0.15
10083987-XXX23TLF	2.30±0.15

mat'l. code				tolerances unless otherwise specified			CUSTOMER COPY		FCI www.fciconnect.com		
ltr	ecn no	dr	date	linear	.X ± 0.38		projection	title			
A	T07-1180	J.H	12/27/07		.XX ± 0.25			PCI-E INTEGRATED TYPE GEN3 CARD EDGE ASS'Y			
B	T10-0030	J.H	1/03/10	angles	.XXX ± 0.10		MM	product family EDGE CARD code			
C	ELX-DG-2161-1	ST	05/27/16		0' ± 2'			size dwg no			
				dr	STONE LI	05/27/15	scale 1:1	A4		10083987	
				enr	STONE LI	05/27/15		sheet			1 of
				chr	/	/		1 of			
				appd	PM ZHENG	05/27/15		1 of			
sheet index	revision sheet	C	C	C			cage code				
	1	2	3				22526				

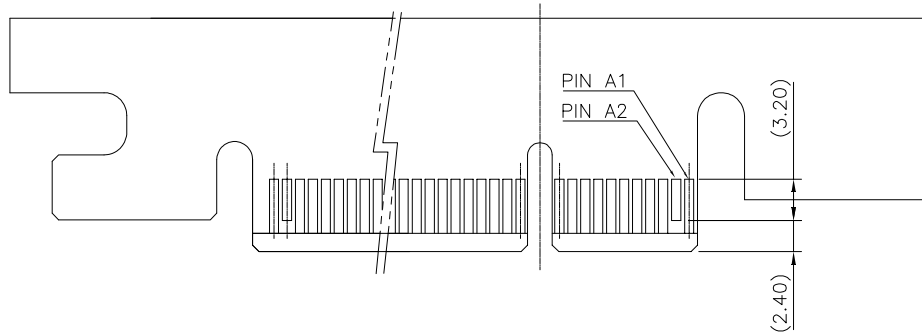
cage code
22526



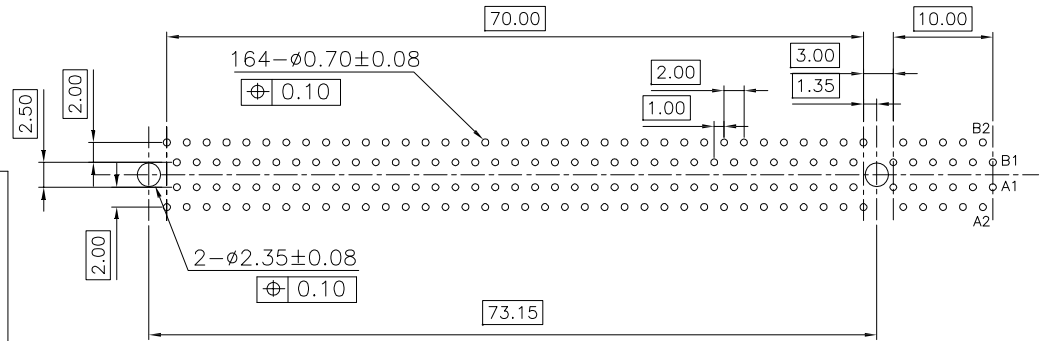
SCALE 2:1

ADD-IN CARD EDGE-FINGER DIMENSIONS

I/O PANEL DIRECTION
PRIMARY (COMPONENT) SIDE



I/O PANEL DIRECTION
SECONDARY (SOLDER) SIDE



RECOMMENDED FOOTPRINT LAYOUT



mat'l. code				tolerances unless otherwise specified			CUSTOMER COPY		 www.fciconnect.com		
ltr	ecn no	dr	date	linear	.X ± 0.38		projection	title PCI-E INTEGRATED TYPE GEN3 CARD EDGE ASS'Y			
					.XX ± 0.25						
					.XXX ± 0.10						
				angles	0° ± 2°		 MM	product family		EDGE CARD	code
				dr	STONE LI	05/27/15		size		dwg no	TWN
				enr	STONF LI	05/27/15		scale		1:1	sheet
				chr	/	/	A4		10083987	2 of	
				appd	PM ZHENG	05/27/15	cage code		22526		
sheet index	revision sheet										

NOTES:

1.MATERIAL:

HOUSING: THERMOPLASTIC WITH GLASS FIBER, UL94V-0,
LATCHS: THERMOPLASTIC WITHOUT GLASS FIBER, UL94-HB (PA66).
CONTACTS: COPPER ALLOY.

2.FINISH:

CONTACTS: GOLD PLATING ON CONTACT AREA,
60u" MATTE TIN (LEAD FREE OPTION) PLATING ON SOLDER TAILS,
50u" MIN. NICKEL UNDERPLATING OVER ALL.

3. WARNING: THE MAXIMUM ALLOWABLE ANGLE TO WITHDRAWAL THE DAUGHTER CARD FROM RETAINER BY 25 DEGREE.

4. DURABILITY: 50 CYCLES.

5. RoHS COMPATIBLE PRODUCT SPECIFICATIONS

- a. PLATING: "LF" MEANS THE PRODUCT IS LEAD FREE, 1.5um min. MATTE PURE TIN OVER 1.27um MIN. NICKEL UNDERPLATE.
- b. MANUFACTURING PROCESS COMPATIBILITY: THE HOUSING WILL WITHSTAND EXPOSURE TO 260C±5C SOLDER BATH TEMPERATURE FOR 5 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.57MM THICK CIRCUIT BOARD.

PRODUCT NUMBER CODE

10083987 -x x x x x x LF

HOUSING COLOR OPTIONS

- 1-BLACK FOR BASE & RM
- 4-BLUE (297C) FOR BASE & RM

PEGS OPTIONS

- 1-PLASTIC POST

TERMINAL PLATING OPTIONS

- 0-50u" Ni UNDERPLATE
30u" Au CONTACT AREA
100u" TIN TAIL AREA
- 1-50u" Ni UNDERPLATE
15u" Au CONTACT AREA
100u" TIN TAIL AREA
- 2-50u" Ni UNDERPLATE
GOLD FLASH CONTACT AREA
100u" TIN TAIL AREA

APPLICATIONS

- LF- LEAD FREE FOR PLATING OPTIONS 0,1,2

PACKAGING OPTIONS

- T-TRAY PACKAGING

POS OPTIONS

- 3-164

TAIL LENGTH OPTION (DIM.A)

- 1- 3.10MM
- 2- 2.30MM



mat'l. code				tolerances unless otherwise specified			CUSTOMER COPY		 www.fciconnect.com		
ltr	ecn no	dr	date	linear	.X ± 0.38	projection	title				
					.XX ± 0.25		PCI-E INTEGRATED TYPE GEN3				
					.XXX ± 0.10		CARD EDGE ASS'Y				
				angles	0° ± 2°	 MM	product family		EDGE CARD	code	
				dr	STONE LI 05/27/15		size		dwg no	TWN	
				engr	STONF LI 05/27/15		A4		10083987	sheet	
				chr	/ /		scale		1:1	3 of	
				appd	PM ZHENG 05/27/15						
sheet index		revision sheet									

cage code
22526